

Dual Interface Technology

Give your card a new identity

Smart Packaging Solutions presents the "Suncombi" platform, a new technology for secured and reliable Dual Interface Cards.

What is the "Suncombi" technology platform?

This technology is based on a specific electromagnetic coupling between an antenna module ("Suncombi" module) and a specific antenna (E-Booster®).

The "Suncombi" module is embedded into a card with the E-Booster®.

Revolutionary for dual interface technology.

The reliability weakness of a common dual interface card is the interconnection between the micro-module and the antenna, embedded into the card body.

With the "Suncombi" technology there is no more interconnection between the module and the antenna. The end products are extremely robust and offer mechanical characteristics never achieved before (**high reliability**).

It is the **easiest** way to manufacture dual interface cards. The embedding process is a standard process used to embed contact modules (**high throughput & yield**).

You do not need to invest in specific & expensive embedding equipment (**No investment**).

Different sizes of modules are available (M4 format...).

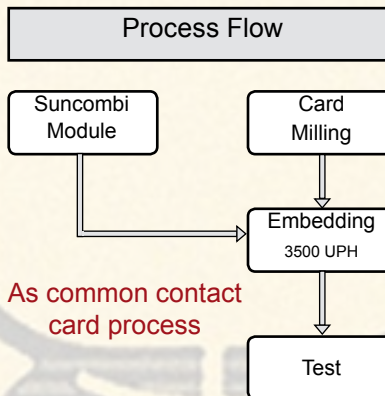
The technology is the only one full compliant with the embossing processes (up to 5 lines).

PRODUCTS

A new way to manufacture Dual-Interface Cards

SPS's offer includes prelaminated antennas and reels of micro-modules ("Suncombi" modules) with/without hotmelt adhesive laminated on the tape.

This semi-finished product enables you to manufacture easily your own dual interface cards by embedding the modules in the cards.



Outstanding Features

- With "Suncombi" technology, there is no more interconnection between the micro-module & the antenna embedded into the card
- High reliability: up to 25 ISO cycles in ISO 10373 bending tests
- Compliant with Paypass and VisaWave
- Contactless applications:
 - Identity (ID, healthcare, driving license cards...)
 - Banking
 - Transport
 - Access control

Technical data

Standard:	ISO/IEC 14443 A/B , 7816, 10373
Frequency:	13.56 MHz
Chip type:	Wide range of chips available (1 Kbyte – 72 Kbytes EEPROM memory)
Module:	
Size:	13.5mm x 16.4mm, R=6.75mm and 11.8x13mm, R=2.2mm M4 format
Handling:	Reel of smart card micro-modules (tape=35mm width)
Adhesive:	With or without adhesive hotmelt laminated on tape

